

Title (en)
POWER ELECTRONIC ARRANGEMENT

Title (de)
LEISTUNGSELEKTRONIKANORDNUNG

Title (fr)
DISPOSITIF ÉLECTRONIQUE DE PUISSANCE

Publication
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Application
EP 11711893 A 20110404

Priority
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Abstract (en)
[origin: WO2011141234A1] Power electronic arrangement (1) comprising a cooling device (2), one or a plurality of capacitors and one or a plurality of circuits, wherein at least one capacitor is electrically connected to at least one circuit, and wherein at least one circuit is arranged on the cooling device, wherein the power electronic arrangement (1) furthermore has a carrier (13) having a carrier base body (14) and at least one connecting element (15) provided for fixing to the cooling device (2), wherein at least one capacitor is accommodated, in particular placed and supported, on the carrier base body (14), and wherein the circuit arranged on the cooling device (2) is arranged on a side of the cooling device (2) which faces the carrier base body (14).

IPC 8 full level
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Citation (search report)
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Citation (examination)
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